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# STPSC806

## 600 V power Schottky silicon carbide diode

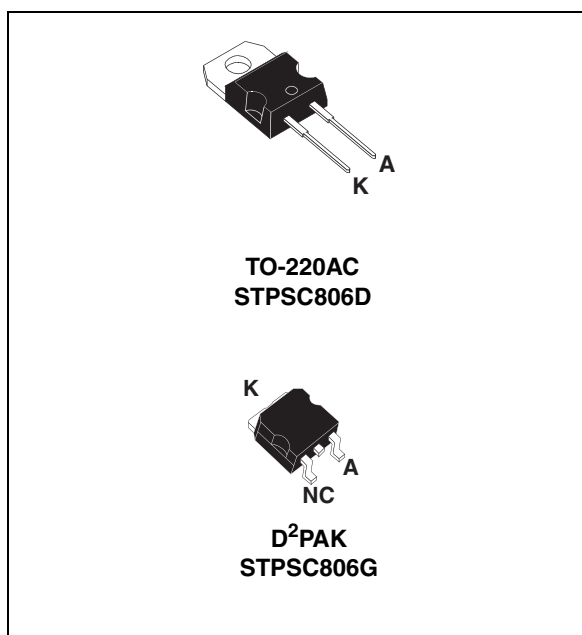
### Features

- No or negligible reverse recovery
- Switching behavior independent of temperature
- Particularly suitable in PFC boost diode function

### Description

The SiC diode is an ultrahigh performance power Schottky diode. It is manufactured using a silicon carbide substrate. The wide band gap material allows the design of a Schottky diode structure with a 600 V rating. Due to the Schottky construction no recovery is shown at turn-off and ringing patterns are negligible. The minimal capacitive turn-off behavior is independent of temperature.

ST SiC diodes will boost the performance of PFC operations in hard switching conditions.



**Table 1. Device summary**

$I_{F(AV)}$	8 A
$V_{RRM}$	600 V
$T_j(max)$	175 °C
$Q_C (typ)$	10 nC

# 1 Characteristics

**Table 2. Absolute ratings (limiting values at 25 °C unless otherwise specified)**

Symbol	Parameter	Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage	600	V
$I_{F(RMS)}$	Forward rms current	18	A
$I_{F(AV)}$	Average forward current	$T_c = 115\text{ °C}, \delta = 0.5$	8
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10\text{ ms sinusoidal}, T_c = 25\text{ °C}$	30
		$t_p = 10\text{ ms sinusoidal}, T_c = 125\text{ °C}$	24
		$t_p = 10\text{ }\mu\text{s square}, T_c = 25\text{ °C}$	120
$I_{FRM}$	Repetitive peak forward current	$T_c = 115\text{ °C}, T_j = 150\text{ °C}, \delta = 0.1,$	30
$T_{stg}$	Storage temperature range	-55 to +175	°C
$T_j$	Operating junction temperature	-40 to +175	°C

**Table 3. Thermal resistance**

Symbol	Parameter	Maximum value	Unit
$R_{th(j-c)}$	Junction to case	2.4	°C/W

**Table 4. Static electrical characteristics**

Symbol	Parameter	Tests conditions	Min.	Typ.	Max.	Unit	
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-	20	100	$\mu\text{A}$
		$T_j = 150\text{ °C}$		-	150	1000	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 8\text{ A}$	-	1.4	1.7	V
		$T_j = 150\text{ °C}$		-	1.6	2.1	

1.  $t_p = 10\text{ ms}, \delta < 2\%$

2.  $t_p = 500\text{ }\mu\text{s}, \delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 1.2 \times I_{F(AV)} + 0.113 \times I_{F(RMS)}^2$$

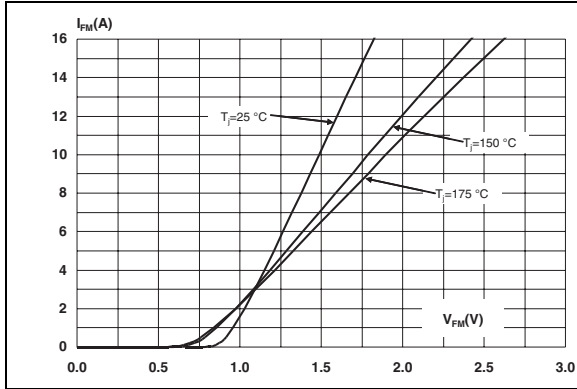
**Table 5. Other parameters**

Symbol	Parameter	Test conditions	Typ.	Unit
$Q_c$	Total capacitive charge	$V_r = 400\text{ V}, I_F = 8\text{ A}, dl_F/dt = -200\text{ A}/\mu\text{s}$ $T_j = 150\text{ °C}$	10	nC
C	Total capacitance	$V_r = 0\text{ V}, T_c = 25\text{ °C}, F = 1\text{ Mhz}$	450	pF
		$V_r = 400\text{ V}, T_c = 25\text{ °C}, F = 1\text{ Mhz}$	35	

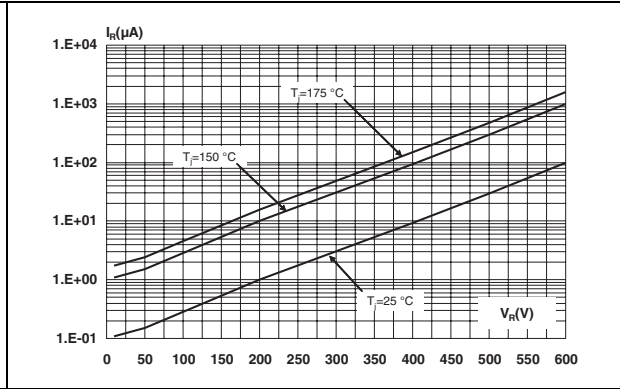
**STPSC806**

**Characteristics**

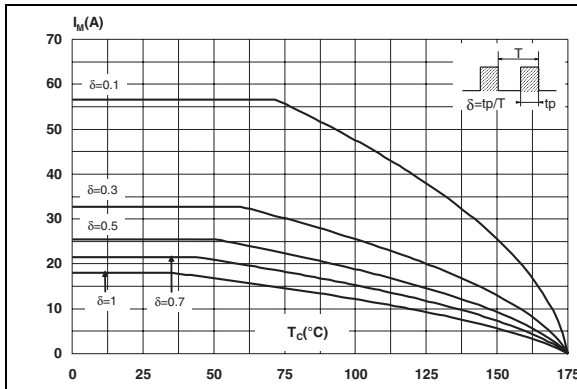
**Figure 1. Forward voltage drop versus forward current (typical values)**



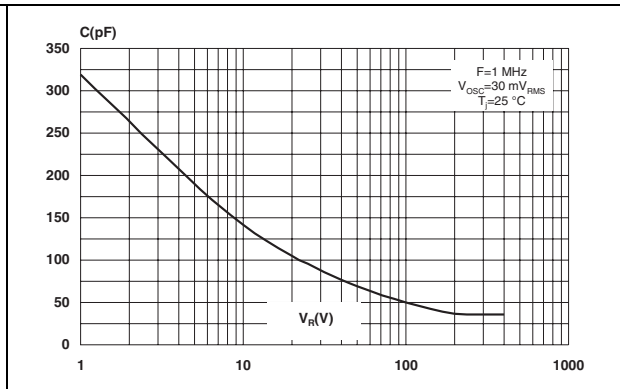
**Figure 2. Reverse leakage current versus reverse voltage applied (maximum values)**



**Figure 3. Peak forward current versus case temperature**



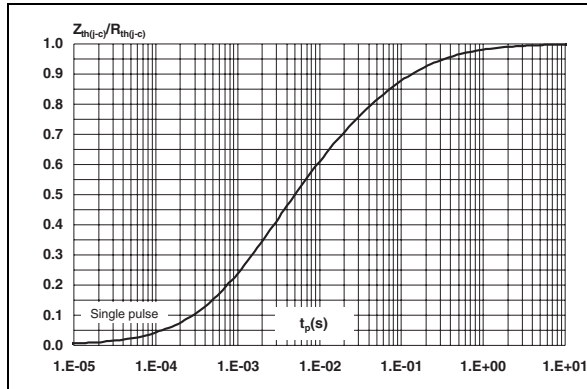
**Figure 4. Junction capacitance versus reverse voltage applied (typical values)**



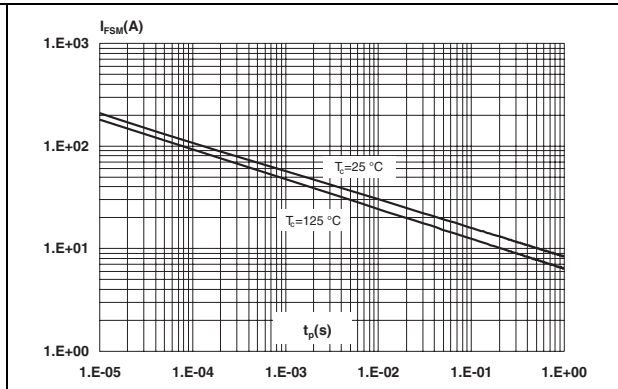
**Characteristics**

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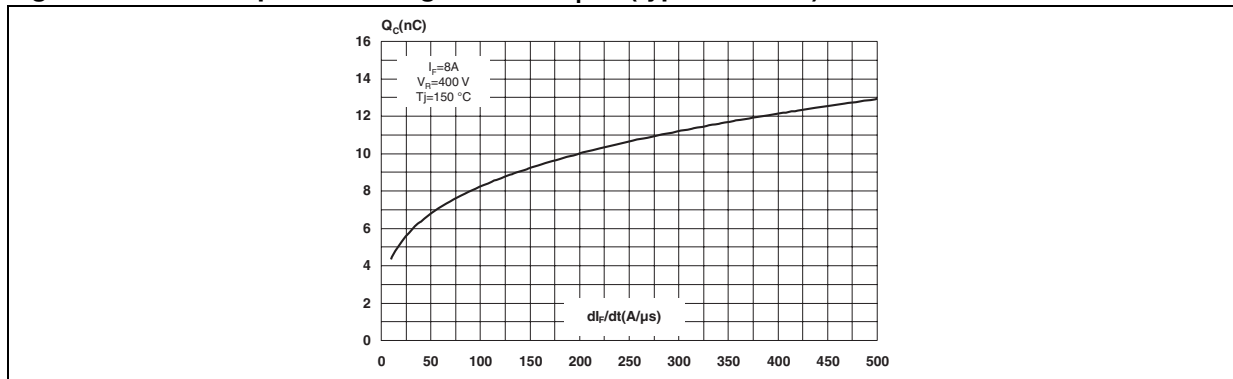
**Figure 5. Relative variation of thermal impedance junction to case versus pulse duration**



**Figure 6. Non-repetitive peak surge forward current versus pulse duration (sinusoidal waveform)**



**Figure 7. Total capacitive charge versus  $di_F/dt$  (typical values)**



## 2 Package information

- Epoxy meets UL94, V0
- Cooling method: convection (C)
- Recommended torque value: 0.4 to 0.6 N·m

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Table 6. TO-220AC dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam. I	3.75	3.85	0.147	0.151

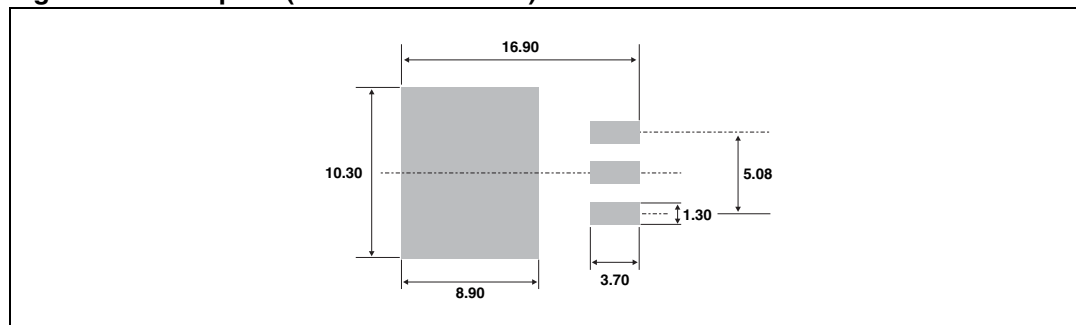
**Package information**

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**Table 7. D<sup>2</sup>PAK dimensions**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

**Figure 8. Footprint (dimensions in mm)**



STPSC806

Ordering information

### 3 Ordering information

Table 8. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPSC806D	STPSC806D	TO-220AC	1.86 g	50	Tube
STPSC806G-TR	STPSC806G	D <sup>2</sup> PAK	1.48 g	1000	Tape and reel

### 4 Revision history

Table 9. Document revision history

Date	Revision	Changes
24-Sep-2009	1	First issue
16-June-2010	2	Added D <sup>2</sup> PAK package.
03-Nov-2010	3	Updated <a href="#">Table 8</a> .



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